L Number	Hits	Search Text	DB	Time stamp
66	0	(29/619).ccls. and (chip adj resistor) and	USPAT;	2003/06/05 15:03
		multilayer	US-PGPUB; IBM TDB	
67	17	(29/611,610.1,619,620,621).ccls. and	USPAT;	2003/06/05 15:05
		substrate and ((etch or etched or etching)	US-PGPUB;	
		with foil) and resistor	IBM TDB	
68	15	(29/610.1,619,620,621).ccls. and substrate	USPAT; .	2003/06/05 15:08
		and ((etch or etched or etching) with	US-PGPUB;	2000,00,00 10.00
		foil) and resistor	IBM TDB	
69	31	(174/260).ccls. and substrate and ((etch	USPAT;	2003/06/05 15:08
		or etched or etching) with foil) and	US-PGPUB;	2000, 00, 00 10100
	:	resistor	IBM TDB	
70	19		USPĀT;	2003/06/05 15:09
. •		or etched or etching) with foil) and	US-PGPUB;	2000,00,00
		resistor and multilayer\$3	IBM TDB	
_	608	29/611.ccls.	USPAT;	2003/06/04 19:12
	000	25,011.0015.	US-PGPUB;	2003/00/04 13:12
			IBM TDB	
_	586	29/\$.ccls. and substrate and ((etch or	USPAT;	2003/06/04 15:56
] 300	etched or etching) with foil)	US-PGPUB;	2003/00/04 13.30
		econed of econing, with fort,	IBM TDB	
_	0	29/\$.ccls. and (photoresistive with	USPAT;	2003/06/04 15:56
		substrate) and ((etch or etched or	US-PGPUB;	2003/00/04 13.30
		etching) with foil)	IBM TDB	
-	4	,	USPAT;	2003/06/04 15:57
	4	substrate) and ((etch or etched or	US-PGPUB;	2003/00/04 13:37
		etching) with foil)	IBM TDB	
_	11		USPAT;	2003/06/04 16:03
	11	layer or coat or coating)) and substrate	US-PGPUB;	2003/00/04 10:03
	ļ	and ((etch or etched or etching) with	IBM TDB	
		foil)	100-100	
_	17	1	USPAT;	2003/06/04 16:11
		layer or coat or coating)) and substrate	US-PGPUB;	2003/00/04 10:11
	1	and ((etch or etched or etching) and foil)	IBM TDB	
_	100	resistor and (resistive adj (film or layer	USPAT;	2003/06/04 16:12
	100	or coat or coating)) and substrate and	US-PGPUB;	2003/00/04 10:12
		((etch or etched or etching) and foil)	IBM TDB	
_	48	((method or process) with resistor) and	USPAT;	2003/06/04 19:49
		(resistive adj (film or layer or coat or	US-PGPUB;	2000,00,01 13.13
		coating)) and substrate and ((etch or	IBM TDB	
		etched or etching) and foil)	15155	
_	7	("4336320" "5466963" "5849355"	USPAT	2003/06/04 16:19
	·	"5872038" "5935642" "5960270"	001111	2000,00,01 10113
		"5994997").PN.		
_	8	("4479890" "4610810" "4870746"	USPAT	2003/06/04 16:30
		"5162144" "5260170" "5338567"		
		"5347258" "5792594").PN.		
_	28	((method or process) with resistor) and	USPAT;	2003/06/04 16:42
		(resistive adj (film or layer or coat or	US-PGPUB;	
	-	coating)) and substrate and (etch or	IBM TDB	
		etched or etching) and foil and width		
_	28	· · · · · · · · · · · · · · · · · · ·	USPAT;	2003/06/04 16:43
		(resistive adj (film or layer or coat or	US-PGPUB;	
		coating)) and substrate and (etch or	IBM TDB	
		etched or etching) and foil with (thick or	_	
	1	thickness or width)		
_	28		USPAT;	2003/06/04 16:48
		(resistive adj (film or layer or coat or	US-PGPUB;	
		coating)) and substrate and (etch or	IBM TDB	
	1	etched or etching) and (foil with (thick		
		or thickness or width))		·
_	32		USPAT;	2003/06/04 19:42
	1	(resistive adj (film or layer or coat or	US-PGPUB;	
	1	coating)) and substrate and ((etch or	IBM TDB	
	1	etched or etching or polishing) with foil)		
	1	conca of counting of portaning, with forth	I	<u> </u>

-	17	("2945180" "3808576" "3813631"	USPAT	2003/06/04 17:03
		"4174513" "4737747" "4888574"		
		"4892776" "5336391" "5422313"		
1		"5483217" "5756971" "5864281"		
		"5907273" "5994997" "6141870"		
		"6232042" "6248612").PN.		0000/06/05 00 15
-	14	(29/611,10.1,620).ccls. and substrate and	USPAT;	2003/06/05 09:15
		((etch or etched or etching) with foil)	US-PGPUB;	
	20	and resistor	IBM_TDB	2002/06/05 00:16
-	38	(338/306-309).ccls. and substrate and ((etch or etched or etching) with foil)	USPAT; US-PGPUB;	2003/06/05 09:16
		and resistor	IBM TDB	
_	3	(338/306-309).ccls. and substrate and	USPAT;	2003/06/05 09:18
		((etch or etched or etching) with foil)	US-PGPUB;	2003/00/03 03:10
		and ((method or processor assembling or	IBM TDB	
	•	making or manufacturing or step) adj		
		resistor)		
-	79	(430/313,315,324).ccls. and substrate and	USPAT;	2003/06/05 09:19
		((etch or etched or etching) with foil)	US-PGPUB;	
			IBM_TDB	
-	13		USPAT;	2003/06/05 09:19
		((etch or etched or etching) with foil)	US-PGPUB;	
	_	and resistor	IBM_TDB	0000/05/05 55 55
_	1	(438/462,977).ccls. and substrate and	USPAT;	2003/06/05 09:20
		(etch or etched or etching) and foil and resistor	US-PGPUB; IBM TDB	
	10			2003/06/05 10:42
_	18	3669022.URPN. 6232042.URPN.	USPAT USPAT	2003/06/05 10:42
_	1	6194990.pn.	USPAT;	2003/06/05 10:40
_	_	0134330.pm.	US-PGPUB;	2003/00/03 11.20
	1		IBM TDB	
_	11	("3719508" "4786564" "4888574"	USPAT	2003/06/05 10:48
		"4892776" "5053318" "5336391"		
		"5347258" "5403672" "5560812"		
		"5679498" "6171921").PN.		
-	11	4297670.URPN.	USPAT	2003/06/05 10:50
-	12	("2945180" "3808576" "3813631"	USPAT	2003/06/05 10:51
		"4174513" "4888574" "4892776"		
		"5336391" "5422313" "5483217"		
	3	"5756971" "5864281" "5907273").PN.	USPAT	2003/06/05 10:52
1 _	11	laminated adj resistor	USPAT;	2003/06/05 10:32
_	1	laminated adj lesistor	US-PGPUB;	2003/00/03 11.21
			IBM TDB	
_	1988	chip adj resistor	USPAT;	2003/06/05 11:30
			US-PGPUB;	
			IBM_TDB	
-	570	(chip adj resistor) and glass	USPĀT;	2003/06/05 11:22
			US-PGPUB;	
1			IBM_TDB	
-	328	(chip adj resistor) and glass and terminal	USPAT;	2003/06/05 11:22
			US-PGPUB;	
1_	126	(chin add register) and along and terminal	IBM_TDB USPAT;	2003/06/05 11:23
-	120	(chip adj resistor) and glass and terminal and nickel	US-PGPUB;	2003/00/03 11:23
		did literet	IBM TDB	
_	126	 (method or process or manufacturing or	USPAT;	2003/06/05 11:24
		making or producing or steps) and (chip	US-PGPUB;	
		adj resistor) and glass and terminal and	IBM TDB	
	1	nickel		
-	11	(method or process or manufacturing or	USPAT;	2003/06/05 11:24
		making or producing or steps) adj (chip	US-PGPUB;	
		adj resistor) and glass and terminal and	IBM_TDB	
		nickel		0000/66/65
_	5	("3167451" "4437140" "4684916"	USPAT	2003/06/05 11:28
	2.5	"5510594" "5680092").PN.	HODAT	2002/06/05 11:30
-	30	(29/610.1,620,621).ccls. and (chip adj	USPAT;	2003/06/05 11:39
		resistor)	US-PGPUB; IBM TDB	
_	10	4267634.URPN.	USPAT	2003/06/05 11:36
L	10	740:004.0IXIN.	1 20111	1 2000,000 11.00

	5	1 (00 (C10 1 C00 C01) 1- and (abin adi		0000/06/05 11 40
-)	(29/610.1,620,621).ccls. and (chip adj	USPAT;	2003/06/05 11:40
		resistor) and multilayer	US-PGPUB;	
		(220 (200 200 220) 1	IBM_TDB	0000/06/05 11 41
_	11	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2003/06/05 11:41
		resistor) and multilayer	US-PGPUB;	
			IBM_TDB	
} -	13		USPAT	2003/06/05 11:42
-	10		USPAT	2003/06/05 11:47
-	1	4267634.pn. and glass	USPAT;	2003/06/05 13:32
			US-PGPUB;	
	1		IBM_TDB	
-	10	4267634.URPN.	USPAT	2003/06/05 13:12
-	0	multilayered adj resistor	USPAT;	2003/06/05 13:16
			US-PGPUB;	
			IBM TDB	
-	8	multi-layered near resistor	USPAT;	2003/06/05 13:20
		_	US-PGPUB;	
			IBM TDB	
_	32723	ceramic near glass	USPAT;	2003/06/05 13:20
			US-PGPUB;	
			IBM TDB	
_	3649	(ceramic near glass) and resistor	USPĀT;	2003/06/05 13:21
		(00000000000000000000000000000000000000	US-PGPUB;	
			IBM TDB	
_	81	(ceramic near glass) and (chip adj	USPAT;	2003/06/05 13:21
	"	resistor)	US-PGPUB;	2003,00,03 13.21
	1	100100017	IBM TDB	
_	0	4267634.pn. and nickel	USPAT;	2003/06/05 13:36
		12070311pm. and michol	US-PGPUB;	2003,00,03 13.30
			IBM TDB	
_	3612	nickel with melting	USPAT;	2003/06/05 13:37
	3012	THERET WICH METERING	US-PGPUB;	2003,00,03 13.3.
			IBM TDB	
_	2226	nickel with (melting adj (point or	USPAT;	2003/06/05 13:38
	2220	temperature))	US-PGPUB;	2003/00/03 13.30
		cemperature//	IBM TDB	
	314	nickel near (melting adj (point or	USPAT;	2003/06/05 13:39
_	314	temperature))	US-PGPUB;	2003/00/03 13.39
		(emperature))	IBM TDB	
	17	nickel near (melting adj (point or	USPAT;	2003/06/05 13:50
_	1	temperature)) and resistor	US-PGPUB;	2003/00/03 13:50
	[cemperature); and resistor		
	9	malladium noon (molting adi (maint	IBM_TDB USPAT;	2003/06/05 13:51
_	9	F		2003/06/05 13:51
		temperature)) and resistor	US-PGPUB;	
	l		IBM_TDB	